Unit: mm

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS III)

TPC6103

Notebook PC Applications Portable Equipment Applications

• Low drain-source ON resistance: RDS (ON) = 29 m Ω (typ.)

• High forward transfer admittance: $|Y_{fs}| = 13 S$ (typ.)

• Low leakage current: $IDSS = -10 \mu A (max) (VDS = -12 V)$

• Enhancement mode: V_{th} = -0.5 to -1.2 V (V_{DS} = -10 V, I_{D} = -200 μA)

Absolute Maximum Ratings (Ta = 25°C)

Characteris	etics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	-12	V	
Drain-gate voltage (R _G	$S = 20 \text{ k}\Omega$)	V_{DGR}	-12	V	
Gate-source voltage		V _{GSS}	±8	V	
Drain current	DC (Note 1)	I _D	-5.5	Α	
Diam current	Pulse (Note 1)	I _{DP}	-22		
Drain power dissipation	(t = 5 s) (Note 2a)	P _D	2.2	W	
Drain power dissipation (t = 5 s) (Note 2b)		P _D	0.7	W	
Single pulse avalanche	e energy (Note 3)	E _{AS}	5.3	mJ	
Avalanche current		I _{AR}	-2.75	Α	
Repetitive avalanche e	nergy (Note 4)	E _{AR}	0.22	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	

1. Drain 50 4. Source
2. Drain 3. Gate 6. Drain

JEDEC —

JEITA —

TOSHIBA 2-3T1A

Weight: 0.011 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

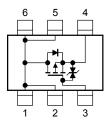
Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient $(t = 5 s)$ (Note 2a)	R _{th (ch-a)}	56.8	°C/W
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	R _{th (ch-a)}	178.5	°C/W

Note: (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5): See the next page.

This transistor is an electrostatic-sensitive device. Please handle with caution.

Circuit Configuration



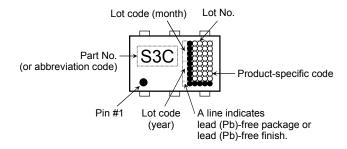
Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cui	rrent	I _{GSS}	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА	
Drain cut-off curr	Drain cut-off current		$V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μΑ	
Drain-source breakdown voltage		V _{(BR)DSS}	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-12	_	_	V	
		V _{(BR)DSX}	$I_D = -10 \text{ mA}, V_{GS} = 8 \text{ V}$	-4	_		V	
Gate threshold v	oltage	V _{th}	$V_{DS} = -10 \text{ V}, I_D = -200 \mu\text{A}$	-0.5	_	-1.2	V	
Drain-source ON resistance		R _{DS (ON)}	$V_{GS} = -1.8 \text{ V}, I_D = -1.4 \text{ A}$	_	65	90		
		R _{DS} (ON)	$V_{GS} = -2.5 \text{ V}, I_D = -2.8 \text{ A}$	_	42	55	$m\Omega$	
		R _{DS} (ON)	$V_{GS} = -4.5 \text{ V}, I_D = -2.8 \text{ A}$	_	29	35		
Forward transfer admittance		Y _{fs}	$V_{DS} = -10 \text{ V}, I_D = -2.8 \text{ A}$	6.5	13	_	S	
Input capacitance		C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	_	1520	_	pF	
Reverse transfer	Reverse transfer capacitance			_	330	_		
Output capacitance		C _{oss}		_	380	_		
Switching time	Rise time	t _r	VGS -5 V ID = -2.8 A OVOUT	_	9.5	_		
	Turn-on time	t _{on}		_	16	_		
	Fall time	tf		_	28	_	ns	
	Turn-off time	t _{off}	$V_{DD} \simeq -6 \text{ V}$ Duty \leq 1%, $t_W =$ 10 μs	_	74	_		
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq -10 \text{ V}, V_{GS} = -5 \text{ V},$	_	20	_		
Gate-source charge		Q _{gs}	$I_D = -5.5 \text{ A}$		15		nC -	
Gate-drain ("miller") charge		Q _{gd}		_	5	_		

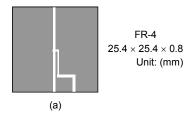
Source-Drain Ratings and Characteristics (Ta = 25°C)

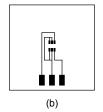
Characteristics Symbol		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	-22	Α
Forward voltage (diode)		V _{DSF}	$I_{DR} = -5.5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

Marking (Note 5)



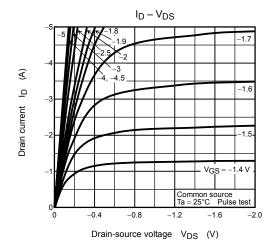
- Note 1: Ensure that the channel temperature does not exceed 150°C.
- Note 2: (a) Device mounted on a glass-epoxy board (a) (t = 5 s)
 - (b) Device mounted on a glass-epoxy board (b) (t = 5 s)

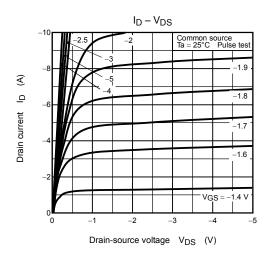


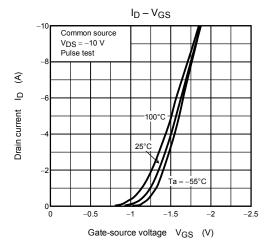


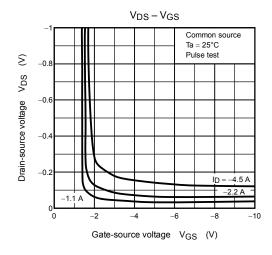
 $\begin{aligned} & \text{FR-4} \\ 25.4 \times 25.4 \times 0.8 \\ & \text{Unit: (mm)} \end{aligned}$

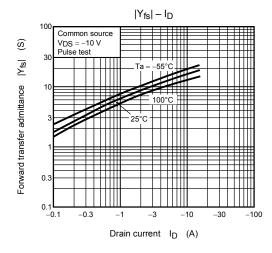
- Note 3: $V_{DD} = -10~V$, $T_{ch} = 25^{\circ}C$ (initial), L = 0.5~mH, $R_G = 25~\Omega$, $I_{AR} = -2.75~A$
- Note 4: Repetitive rating: pulse width limited by maximum channel temperature
- Note 5: on lower left of the marking indicates Pin 1.

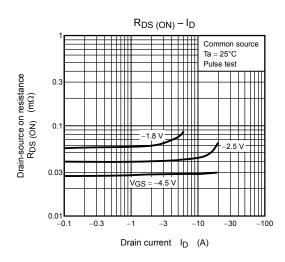




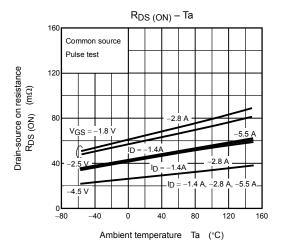


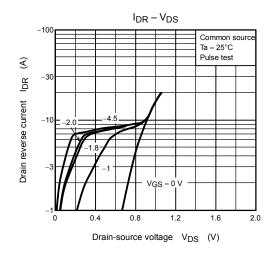


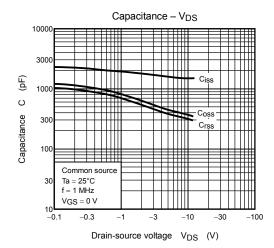


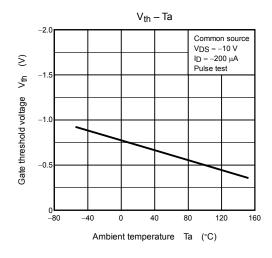


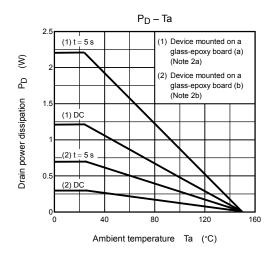
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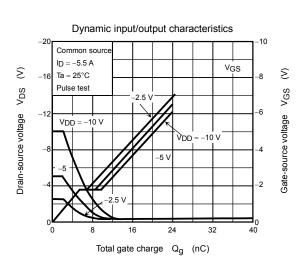


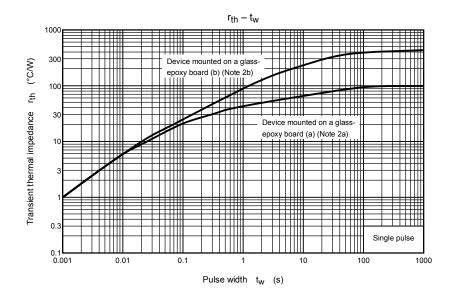


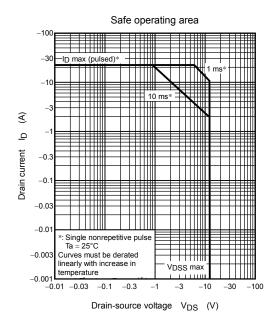












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